

ASSP Fractional-N PLL Frequency Synthesizer

MB15F88UL

■ DESCRIPTION

The Fujitsu MB15F88UL is Fractional-N Phase Locked Loop (PLL) frequency synthesizer with fast lock up functional. The Fractional-N PLL operating up to 2600MHz and the integer PLL operating up to 1200MHz are integrated on one chip.

MB15F88UL is used charge pump which is well-balanced output current with 1.5mA and 6mA selectable by serial data, direct power save control and digital lock detector. In addition, MB15F88UL adopts a new architecture to achieve fast lock.

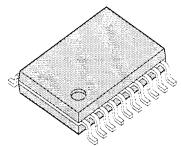
The new package(Thin Bump Chip Carrier20) decreases a mount area of MB15F88UL more than 30% comparing with the former B.C.C.16(for dual PLL, MB15F08SL).

MB15F88UL is ideally suited for wireless mobile communications, such as W-CDMA.

■ FEATURES

- High frequency operation: RX synthesizer : 2600MHz max
TX synthesizer: 1200MHz max
- Low power supply voltage: $V_{cc} = 2.7$ to 3.6 V
- Ultra Low power supply current : $I_{cc} = 6.0$ mA typ. ($V_{cc} = V_p=3.0V$, $T_a=25^{\circ}\text{C}$ in TX, RX locking state)
- Direct power saving function : Power supply current in power saving mode
Typ. $0.1 \mu\text{A}$ ($V_{cc}=V_p=3.0\text{V}$, $T_a=25^{\circ}\text{C}$), Max. $10 \mu\text{A}$ ($V_{cc}=V_p=3.0\text{V}$)
- Fractional function : selectable modulo 5 or 8/ Acheiving fast lock and low phase noise(Implemented in RX)
- Dual modulus prescaler : 2600MHz prescaler(32/33fixed) / 1200MHz prescaler(16/17 or 32/33)
- Serial input 14-bit programmable reference divider: $R = 8$ to $16,383$
- Serial input programmable divider consisting of:
 - RX section -Binary 5-bit swallow counter: 0 to 31
 - Binary 10-bit programmable counter: 34 to 1,023
 - Binary 4-bit fractional counter numerator: 0 to 15
 - TX section -Binary 5-bit swallow counter: 0 to 31
 - Binary 11-bit programmable counter: 3 to 2,047
- On-chip phase comparator for fast lock and low noise
- Operating temperature: $T_a = -40$ to 85°C
- Small package Bump Chip Carrier.0(3.4mm*3.6mm*0.6mm)

20-pin, Plastic TSSOP

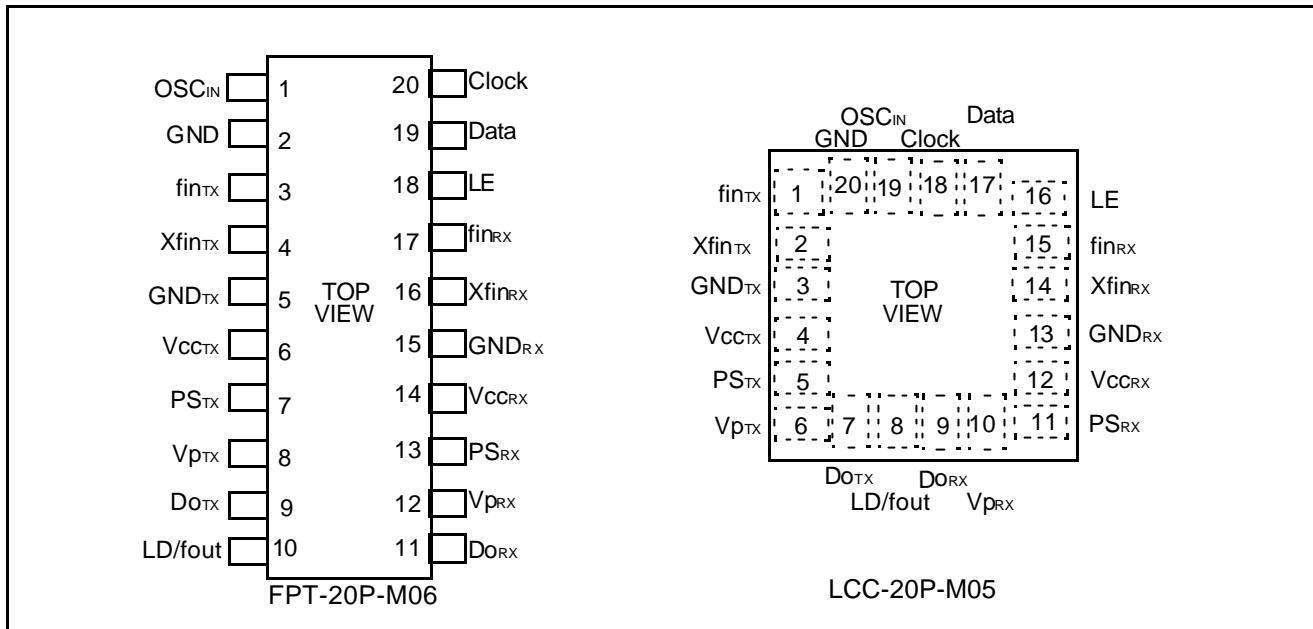


(FPT-20P-M06)

20-pad, Plastic BCC



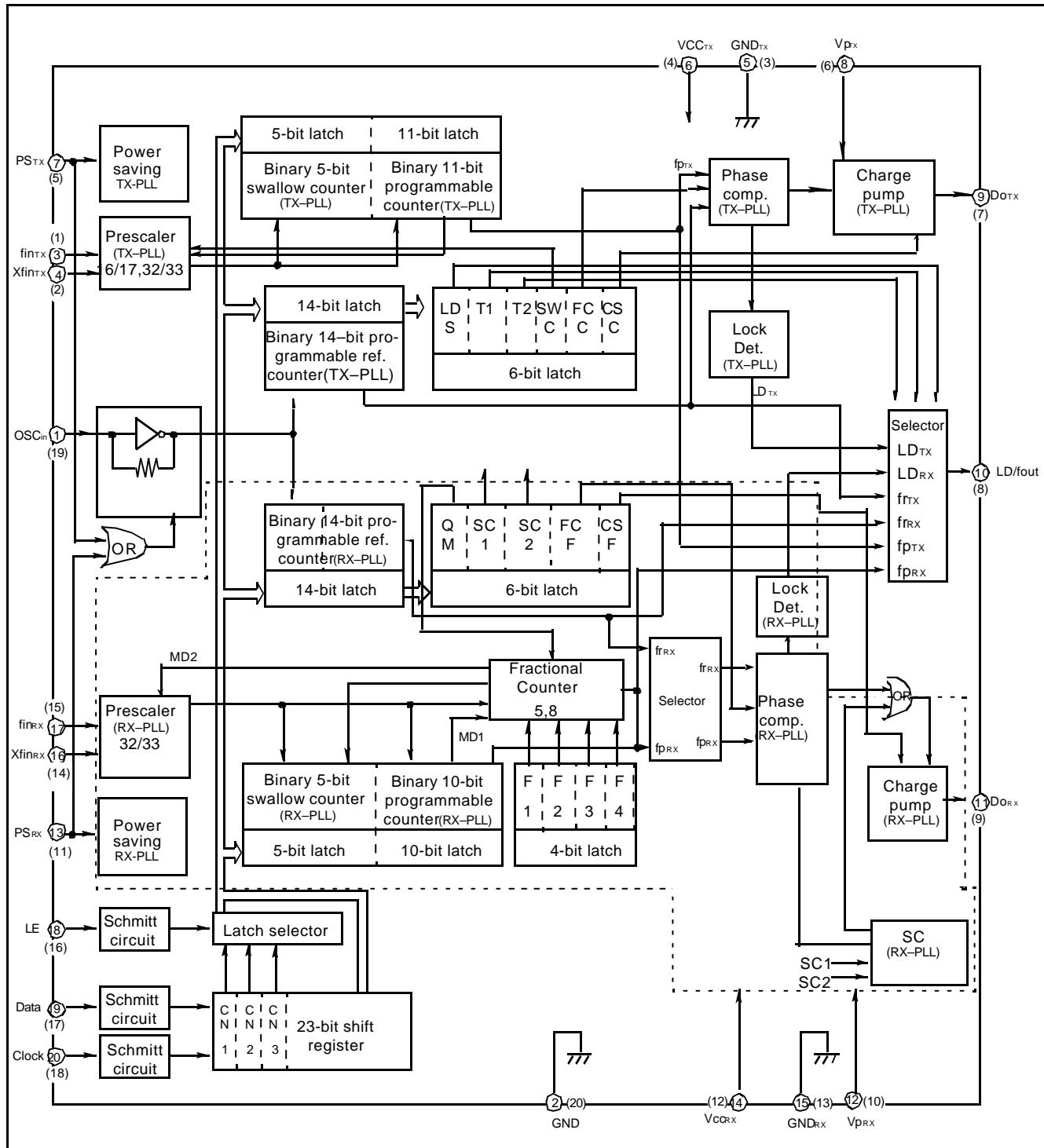
(LCC-20P-M05)

■ PIN ASSIGNMENT

■ PIN DESCRIPTIONS

Pin No.		Pin name	I/O	Descriptions
TSSOP	BCC			
1	19	OSC _{in}	I	The programmable reference divider input. TCXO should be connected with a AC coupling capacitor.
2	20	GND	-	Ground for OSC input buffer and the shift register circuit.
3	1	f _{in} _{TX}	I	Prescaler input pin for the TX-PLL. Connection to an external VCO should be AC coupling.
4	2	Xf _{in} _{TX}	I	Prescaler complimentary input for the TX-PLL section. This pin should be grounded via a capacitor.
5	3	GND _{TX}	-	Ground for the TX-PLL section.
6	4	V _{cctx}	-	Power supply voltage input pin for the TX-PLL section(except for the charge pump circuit), the shift register and the oscillator input buffer. When power is OFF, latched data of TX-PLL is lost.
7	5	PS _{TX}	I	Power saving mode control for the TX-PLL section. This pin must be set at "L" Power-ON. (Open is prohibited.) PS _{TX} = "H" ; Normal mode, PS _{TX} = "L" ; Power saving mode
8	6	V _p _{TX}	-	Power supply voltage input pin for the TX-PLL charge pump.
9	7	D _o _{TX}	O	Charge pump output for the TX-PLL section. Phase characteristics of the phase detector can be reversed by FC-bit.
10	8	LD/fout	O	Lock detect signal output(LD)/ phase comparator monitoring output (fout). The output signal is selected by a LDS bit in a serial data. LDS bit = "H" ; outputs fout signal, LDS bit = "L" ; outputs LD signal
11	9	D _o _{RX}	O	Charge pump output for the RX-PLL section. Phase characteristics of the phase detector can be reversed by FC-bit.
12	10	V _p _{RX}	-	Power supply voltage input pin for the RX-PLL charge pump.
13	11	PS _{RX}	I	Power saving mode control for the RX-PLL section. This pin must be set at "L" Power-ON. (Open is prohibited.) PS _{RX} = "H" ; Normal mode, PS _{RX} = "L" ; Power saving mode
14	12	V _{ccrx}	-	Power supply voltage input pin for the RX-PLL section(except for the charge pump circuit).
15	13	GND _{RX}	-	Ground for the RX-PLL section.
16	14	Xf _{in} _{RX}	I	Prescaler complimentary input for the RX-PLL section. This pin should be grounded via a capacitor.
17	15	f _{in} _{RX}	I	Prescaler input pin for the RX-PLL. Connection to an external VCO should be AC coupling.
18	16	LE	I	Load enable signal input (with the schmitt trigger circuit.) On a rising edge of load enable, data in the shift register is transferred to the corresponding latch according to the control bit in a serial data.
19	17	Data	I	Serial data input (with the schmitt trigger circuit.) A data is transferred to the corresponding latch (TX-ref counter, TX-prog. counter, RX-ref. counter, RX-prog. counter) according to the control bit in a serial data.
20	18	Clock	I	Clock input for the 23-bit shift register (with the schmitt trigger circuit.) One bit data is shifted into the shift register on a rising edge of the clock.

■ BLOCK DIAGRAM



O -- TSSOP 20
() -- BCC 20

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating		Unit	Remark
		Min.	Max.		
Power supply voltage	V _{cc}	-0.5	+4.0	V	
	V _p	V _{cc}	+4.0	V	
Input voltage	V _I	-0.5	V _{cc} +0.5	V	
Output voltage	V _o	GND	V _{cc}	V	LD/fout
	V _{bo}	GND	V _p	V	Do
Storage temperature	T _{stg}	-55	+125	°C	

Note: Permanent device damage may occur if the above **Absolute Maximum Ratings** are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Power supply voltage	V _{cc}	2.7	3.0	3.6	V	V _{CCRX} = V _{CCTX}
	V _p	V _{cc}	3.0	3.6	V	
Input voltage	V _I	GND	-	V _{cc}	V	
Operating temperature	T _a	-40	-	+85	°C	

Handling Precautions

- (1) V_{CCRX}, V_{PRX}, V_{CCTX} and V_{P TX} must supply equal voltage.
Even if either RX-PLL or TX-PLL is not used, power must be supplied to both V_{CCRX}, V_{P RX}, V_{CCTX} and V_{P TX} to keep them equal. It is recommended that the non-use PLL is controlled by power saving function.
- (2) To protect against damage by electrostatic discharge, note the following handling precautions:
 - Store and transport devices in conductive containers.
 - Use properly grounded workstations, tools, and equipment.
 - Turn off power before inserting or removing this device into or from a socket.
 - Protect leads with conductive sheet, when transporting a board mounted device.

■ ELECTRICAL CHARACTERISTICS

(V_{CC} = 2.7 to 3.6 V, Ta = -40 to +85°C)

Parameter	Symbol	Condition	Value			Unit	
			Min.	Typ.	Max.		
Power supply current* ¹	I _{CC_{TX}} * ¹	f _{IN_{TX}} =910MHz V _{CC_{TX}} =V _{P_{TX}} =3.0V, SWC=0	1.3	2.0	2.8	mA	
	I _{CC_{RX}} * ¹	f _{IN_{RX}} =2500MHz V _{CC_{RX}} =V _{P_{RX}} =3.0V	2.6	4.0	5.6	mA	
Power saving current	I _{P_{STX}}	PS= "L"	—	0.1 ²	10	μA	
	I _{P_{SRX}}	PS= "L"	—	0.1 ²	10	μA	
Operating frequency	f _{IN_{TX}} * ³	f _{IN_{TX}}	TX PLL	100	—	1200	MHz
	f _{IN_{RX}} * ³	f _{IN_{RX}}	RX PLL	1700	—	2600	MHz
	OSC _{IN}	fosc	—	3	—	40	MHz
Input sensitivity	f _{IN_{TX}}	Pf _{IN_{TX}}	TX PLL, 50 Ω system	-15	—	+2	dBm
	f _{IN_{RX}}	Pf _{IN_{RX}}	RX PLL, 50 Ω system	-15	—	+2	dBm
	OSC _{IN}	V _{OSC}	—	0.5	—	V _{CC}	V _{p-p}
"H" level Input voltage	Data, Clock, LE	V _{IH}	Schmitt trigger input	V _{CC} × 0.7+0.4	—	—	V
"L" level Input voltage		V _{IL}	Schmitt trigger input	—	—	V _{CC} × 0.3-0.4	
"H" level Input voltage	PS	V _{IH}	—	V _{CC} × 0.7	—	—	V
"L" level Input voltage		V _{IL}	—	—	—	V _{CC} × 0.3	
"H" level Input current	Data, Clock, LE, PS	I _{IH} * ⁴	—	-1.0	—	+1.0	μA
"L" level Input current		I _{IL} * ⁴	—	-1.0	—	+1.0	
"H" level Input current	OSC _{IN}	I _{IH}	—	0	—	+100	μA
"L" level Input current		I _{IL} * ⁴	—	-100	—	0	
"H" level output voltage	LD/fout	V _{OH}	V _{CC} =V _P =3.0V, I _{OH} =-1mA	V _{CC} − 0.4	—	—	V
"L" level output voltage		V _{OL}	V _{CC} =V _P =3.0V, I _{OL} =1mA	—	—	0.4	
"H" level output voltage	D _{O_{TX}} D _{O_{RX}}	V _{D_{OH}}	V _{CC} =V _P =3.0V, I _{D_{OH}} =-0.5mA	V _P − 0.4	—	—	V
"L" level output voltage		V _{D_{OL}}	V _{CC} =V _P =3.0V, I _{D_{OL}} =0.5mA	—	—	0.4	
High impedance cutoff current	D _{O_{TX}} D _{O_{RX}}	I _{OFF}	V _{CC} =3.0V, V _{OFF} =0.5V to V _P -0.5V	—	—	2.5	nA
"H" level Output current	LD/fout	I _{OH} * ⁴	V _{CC} = V _P = 3.0V	—	—	-1.0	mA
"L" level Output current		I _{D_{OL}} * ⁴	V _{CC} = V _P = 3.0V	1.0	—	—	

(Continued)

(Continued)

($V_{CC} = 2.7$ to 3.6 V, $T_a = -40$ to $+85^\circ\text{C}$)

Parameter	Symbol	Condition	Value			Unit	
			Min.	Typ.	Max.		
"H" level Output current	I_{DOH}^{*4} D_{OTX} D_{ORX}	$V_{CC}=V_p=3.0$ V $V_{DOH}=V_p/2$ $T_a=25^\circ\text{C}$	CS bit = "H"	-8.2	-6.0	-4.1	mA
			CS bit = "L"	-2.2	-1.5	-0.8	
"L" level Output current	I_{DOL}	$V_{CC}=V_p=3.0$ V $V_{DOL}=V_p/2$ $T_a=25^\circ\text{C}$	CS bit = "H"	4.1	6.0	8.2	
			CS bit = "L"	0.8	1.5	2.2	
Charge pump current rate	I_{DOL}/I_{DOH}	I_{DOMT}^{*5}	$V_{DO}=V_p/2$	-	3	-	%
	vs V_{DO}	I_{DOVD}^{*6}	$0.5\text{V} \leq V_{DO} \leq V_p-0.5\text{V}$	-	10	-	%
	vs T_a	I_{DOTA}^{*7}	$-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$, $V_{DO}=V_p/2$	-	5	-	%

*1: Conditions; fosc=13MHz, $T_a = 25^\circ\text{C}$ in locking state.

*2: $V_{CC_{TX}}=V_{P_{TX}}=V_{CC_{RX}}=V_{P_{RX}}=3.0$ V, fosc=13MHz, $T_a = 25^\circ\text{C}$, in power saving mode.

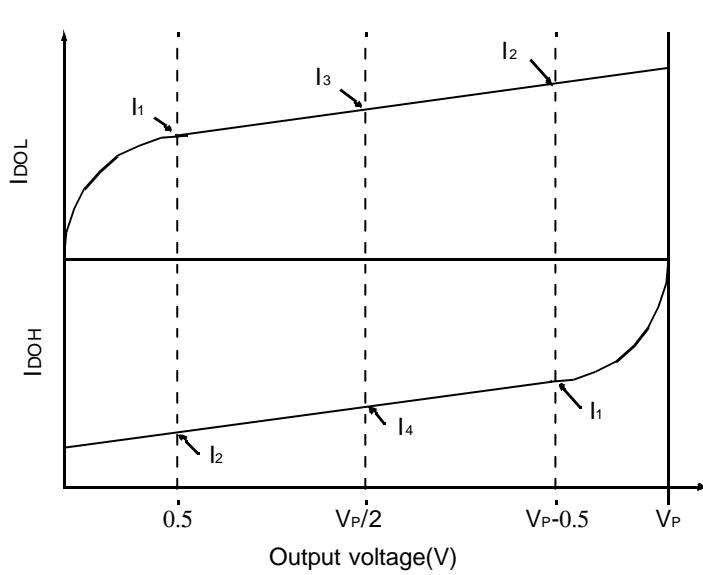
*3: AC coupling. 1000pF capacitor is connected.

*4: The symbol "-"(minus) means direction of current flow.

*5: $V_{CC}=V_p=3.0$ V, $T_a=25^\circ\text{C}$ $((|I_3| - |I_4|) / [|I_3| + |I_4|] / 2) \times 100\% \text{ (Applied to each } I_{DOL}, I_{DOH})$

*6: $V_{CC}=V_p=3.0$ V, $T_a=25^\circ\text{C}$ $((|I_2| - |I_1|) / [|I_1| + |I_2|] / 2) \times 100\% \text{ (Applied to each } I_{DOL}, I_{DOH})$

*7: $V_{CC}=V_p=3.0$ V, $((|I_{DO(85C)}| - |I_{DO(-40C)}|) / 2) / ((|I_{DO(85C)}| + |I_{DO(-40C)}|) / 2) \times 100\% \text{ (Applied to each } I_{DOL}, I_{DOH})$



■ FUNCTIONAL DESCRIPTIONS

Serial Data Input

Serial data is entered using three pins, Data pin, Clock pin, and LE pin. Programmable dividers of TX/RX-PLL sections, programmable reference dividers of TX/RX-PLL sections are controlled individually.

Serial data of binary data is entered through Data pin.

On a rising edge of clock, one bit of serial data is transferred into the shift register. On a rising edge of load enable signal, the data stored in the shift register is transferred to one of latch of them depending upon the control bit data setting.

Table1. Control Bit

(CN3=1 is prohibited)

Control bit			Destination of serial data																
CN1	CN2	CN3																	
0	0	0	The programmable reference counter for the TX-PLL.																
1	0	0	The programmable counter and the swallow counter for the TX-PLL																
0	1	0	The programmable reference counter for the RX-PLL.																
1	1	0	The programmable counter and the swallow counter for the RX-PLL																

Table2. Serial data format

LLSB		Direction of data shift →																			MSB	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23
0	0	0	Rc ₁	Rc ₂	Rc ₃	Rc ₄	Rc ₅	Rc ₆	Rc ₇	Rc ₈	Rc ₉	Rc ₁₀	Rc ₁₁	Rc ₁₂	Rc ₁₃	Rc ₁₄	LD _S	T ₁	T ₂	Sw _c	FC _c	CS _c
1	0	0	Ac ₁	Ac ₂	Ac ₃	Ac ₄	Ac ₅	0	0	Nc ₁	Nc ₂	Nc ₃	Nc ₄	Nc ₅	Nc ₆	Nc ₇	Nc ₈	Nc ₉	Nc ₁₀	Nc ₁₁	X	X
0	1	0	RF ₁	RF ₂	RF ₃	RF ₄	RF ₅	RF ₆	RF ₇	RF ₈	RF ₉	RF ₁₀	RF ₁₁	RF ₁₂	RF ₁₃	RF ₁₄	Q _M	SC ₁	SC ₂	1	FC _F	CS _F
1	1	0	AF ₁	AF ₂	AF ₃	AF ₄	AF ₅	NF ₁	NF ₂	NF ₃	NF ₄	NF ₅	NF ₆	NF ₇	NF ₈	NF ₉	NF ₁₀	F ₁	F ₂	F ₃	F ₄	0



- Rc1 to Rc14 : Divide ratio setting bits for the reference counter of the TX(8 to 16383)
- Ac1 to Ac5 : Divide ratio setting bits for the swallow counter of the TX (0 to 31, A<N)
- Nc1 to Nc11 : Divide ratio setting bits for the programmable counter of the TX(3 to 2047)
- LDS,T1,T2 : Select bits for the lock detect output or a monitoring phase comparison frequency
- SWc : Divide ratio setting for the prescaler of the TX
- FCc : Phase control bit for the phase detector of the TX
- CSc : Charge pump current select bit of the TX
- RF1 to RF14 : Divide ratio setting bits for the reference counter of the RX(8 to 16383)
- AF1 to AF5 : Divide ratio setting bits for the swallow counter of the RX (0 to 31, A<N-2)
- NF1 to NF10 : Divide ratio setting bits for the programmable counter of the RX(34 to 1023)
- F1 to F4 : Fractional-N increment setting bit for the fractional accumulator (0 to 15, F<Q)
- QM : Fractional-N modulus selection bit. "1" modulus=8, "0" modulus=5
- SC1,SC2 : Spurious cancel set bit of the RX.
- FCF : Phase control bit for the phase detector of the RX.
- CSF : Charge pump current select bit of the RX
- X : Dummy bit(Set "0" or "1")

1)RX synthesizer Data Setting(Fractional-N)

The divide ratio can be calculated using the following equation:

$$f_{VCOX} = N_{TOTAL} \times f_{osc} / R$$

$$N_{TOTAL} = P \times N + A + F/Q \quad (A < N-2, F < Q)$$

f_{VCOX} :Output frequency of external voltage controlled oscillator(VCO)
N_{TOTAL} :Total division ratio from prescaler input to the phase deector input
f_{osc} :Output frequency of the reference frequency oscillator
R :Preset divide ratio of binary 14bit reference counter(8 to 16383)
P :Preset divide ratio of modulus prescaler(32 fixed)
N :Preset divide ratio of binary 10bit programmable counter(34 to 1023)
A :Preset divide ratio of binary 5 bit swallow counter(0 to 31)
F :A numerator of fractional-N.(0 to 15)
Q :A denominator of fractional-N. "QM bit=1" modulo 8, "QM bit=0" modulo 5

Table3. Binary 14-bit Programmable Reference Counter Data Setting(RF1 to RF14)

Divide ratio (R)	RF 14	RF 13	RF 12	RF 11	RF 10	RF 9	RF 8	RF 7	RF 6	RF 5	RF 4	RF 3	RF 2	RF 1
8	0	0	0	0	0	0	0	0	0	0	1	0	0	0
9	0	0	0	0	0	0	0	0	0	0	1	0	0	1
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
52	0	0	0	0	0	0	0	0	1	1	0	1	0	0
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: • Divide ratio less than 8 is prohibited.

Table4. Fractional-N modulo Data Setting(Q)

QM	Modulo-Q
0	5
1	8

Table5. Fractional-N increment of the fractional accumulator Data setting(F1 to F4)

Setting value(F)	F4	F3	F2	F1
0	0	0	0	0
1	0	0	0	1
2	0	0	1	0
-	-	-	-	-
15	1	1	1	1

Note: • F<Q

Table.6 Binary 10-bit Programmable Counter Data Setting(NF1 to NF10)

Divide ratio (N)	NF 10	NF 9	NF 8	NF 7	NF 6	NF 5	NF 4	NF 3	NF 2	NF 1
34	0	0	0	0	1	0	0	0	1	0
35	0	0	0	0	1	0	0	0	1	1
-	-	-	-	-	-	-	-	-	-	-
64	0	0	0	1	0	0	0	0	0	0
-	-	-	-	-	-	-	-	-	-	-
1023	1	1	1	1	1	1	1	1	1	1

Note: • Divide ratio less than 34 is prohibited.

Table.7 Binary 5-bit Swallow Counter Data Setting(AF1 to AF5)

Divide ratio (N)	AF 5	AF 4	AF 3	AF 2	AF 1
0	0	0	0	0	0
1	0	0	0	0	1
2	0	0	0	1	0
-	-	-	-	-	-
15	1	1	1	1	1

Note: • A<N-2

Table.8 Charge pump current select Bit Setting

CSF	Current value
1	+/-6.0mA
0	+/-1.5mA

Table.9 Spurious cancel Bit Setting

Spurious cancel amount	SC1	SC2
Large	0	0
Midium	0	1
Small	1	0

2) TX synthesizer Data Setting(Integer)

The divide ratio can be calculated using the following equation:

$$f_{VCOx} = [(P \times N) + A] f_{osc} / R \quad (A < N)$$

f_{VCOx}: Output frequency of external voltage controlled oscillator(VCO)
 P : Preset divide ratio of modulus prescaler(16 or 32)
 N : Preset divide ratio of binary 11bit programmable counter(3 to 2047)
 A : Preset divide ratio of binary 5 bit swallow counter(0 to 31)
 f_{osc} : Output frequency of the reference frequency oscillator
 R : Preset divide ratio of binary 14bit reference counter(8 to 16383)

Table10. Binary 14-bit Programmable Reference Counter Data Setting(RC1 to RC14)

Divide ratio (R)	Rc 14	Rc 13	Rc 12	Rc 11	Rc 10	Rc 9	Rc 8	Rc 7	Rc 6	Rc 5	Rc 4	Rc 3	Rc 2	Rc 1
8	0	0	0	0	0	0	0	0	0	0	1	0	0	0
9	0	0	0	0	0	0	0	0	0	0	1	0	0	1
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: • Divide ratio less than 8 is prohibited.

Table.11 Binary 11-bit Programmable Counter Data Setting (NC1 to NC11)

Divide ratio (N)	Nc 11	Nc 10	Nc 9	Nc 8	Nc 7	Nc 6	Nc 5	Nc 4	Nc 3	Nc 2	Nc 1
3	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	1	0	0
-	-	-	-	-	-	-	-	-	-	-	-
2047	1	1	1	1	1	1	1	1	1	1	1

Note: • Divide ratio less than 3 is prohibited.

Table.12 Binary 5-bit Swallow Counter Data Setting(AC1 to AC5)

Divide ratio (N)	Ac 5	Ac 4	Ac 3	Ac 2	Ac 1
0	0	0	0	0	0
1	0	0	0	0	1
2	0	0	0	1	0
-	-	-	-	-	-
31	1	1	1	1	1

Note: • A < N

Table. 13 Prescaler Data Setting(SWc)

SWc	Prescaler divide ratio
1	16/17
0	32/33

Table. 14 Charge pump current select Data Setting(CSC)

CSc	Do current
1	+/-6.0mA
0	+/-1.5mA

3)Common setting**Table. 15 LD/fout Output Select Data Setting**

LD/fout	LDS	T1	T2
LD output	0	-	-
fout output	f _{RTX}	1	0
	f _{RX}	1	1
	f _{PTX}	1	0
	f _{PRX}	1	1

Table. 16 Phase Comparator Phase Switching Data Setting

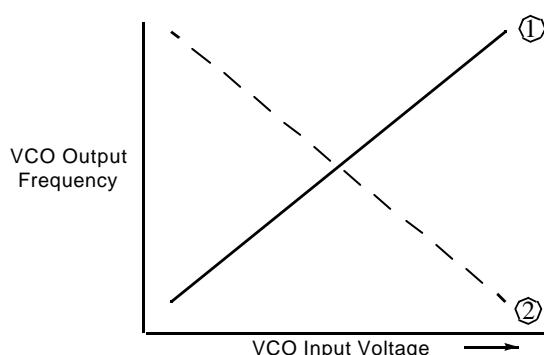
	F _{CF/C} = H	F _{CF/C} = L
	D _{OTX,RX}	
f _r > f _p	H	L
f _r = f _p	Z	Z
f _r < f _p	L	H
VCO polarity	1	2

- Note:
- Z = High-impedance
 - Depending upon the VCO and LPF polarity, FC bit should be set.

When designing a synthesizer, the FC bit setting depends on the VCO and LPF characteristics

When the LPF and VCO characteristics are similar to (1),
set FC bit "High".

When the VCO characteristics are similar to (2),
set FC bit "Low"



4. Power Saving Mode (Intermittent Mode Control)

Table 17. PS Pin Setting

PS pin	Status
H	Normal mode
L	Power saving mode

The intermittent mode control circuit reduces the PLL power consumption.

By setting the PS pin low, the device enters into the power saving mode, reducing the current consumption. See the Electrical Characteristics chart for the specific value.

The phase detector output, Do, becomes high impedance.

For the single PLL, the lock detector, LD, remains high, indicating a locked condition.

For the dual PLL, the lock detector, LD, is as shown in the LD Output Logic table.

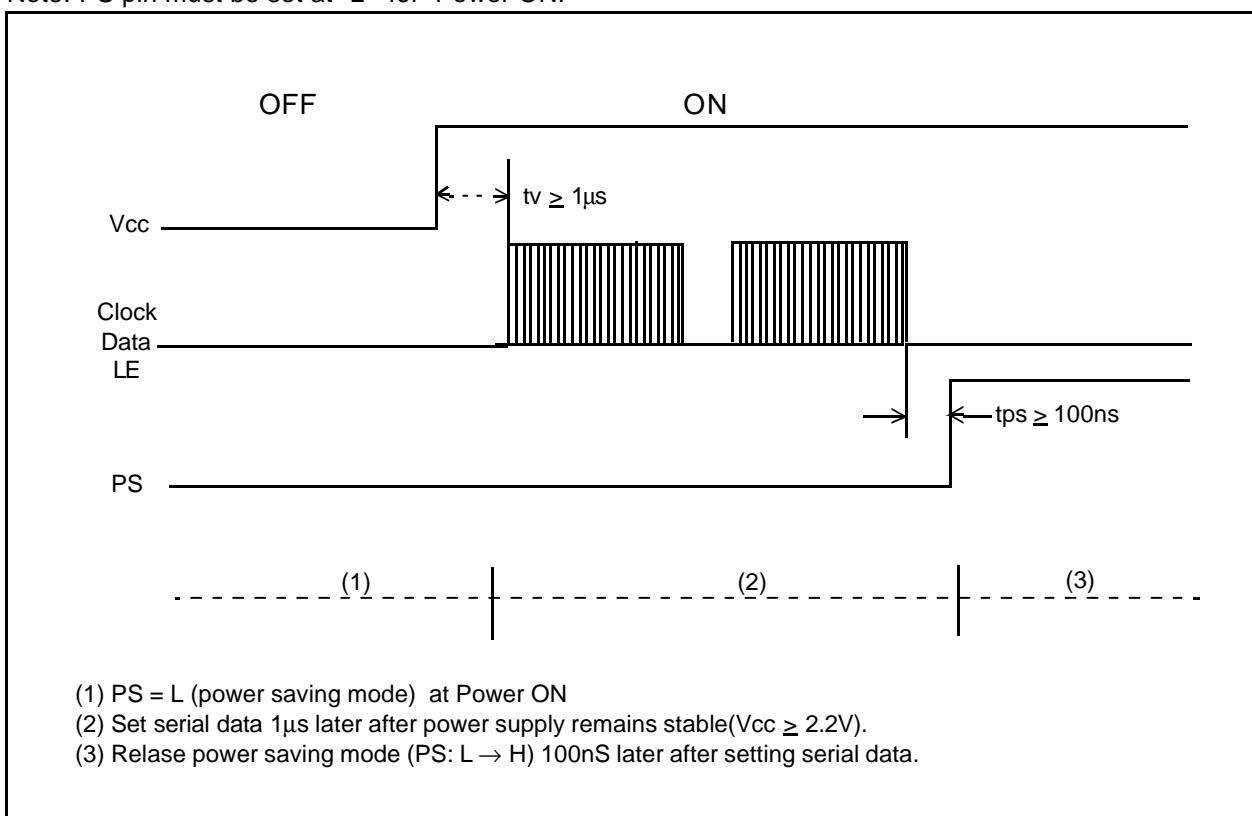
Setting the PS pin high, releases the power saving mode, and the device works normally.

The intermittent mode control circuit also ensures a smooth startup when the device returns to normal operation. When the PLL is returned to normal operation, the phase comparator output signal is unpredictable. This is because of the unknown relationship between the comparison frequency (f_p) and the reference frequency (f_r) which can cause a major change in the comparator output, resulting in a VCO frequency jump and an increase in lockup time.

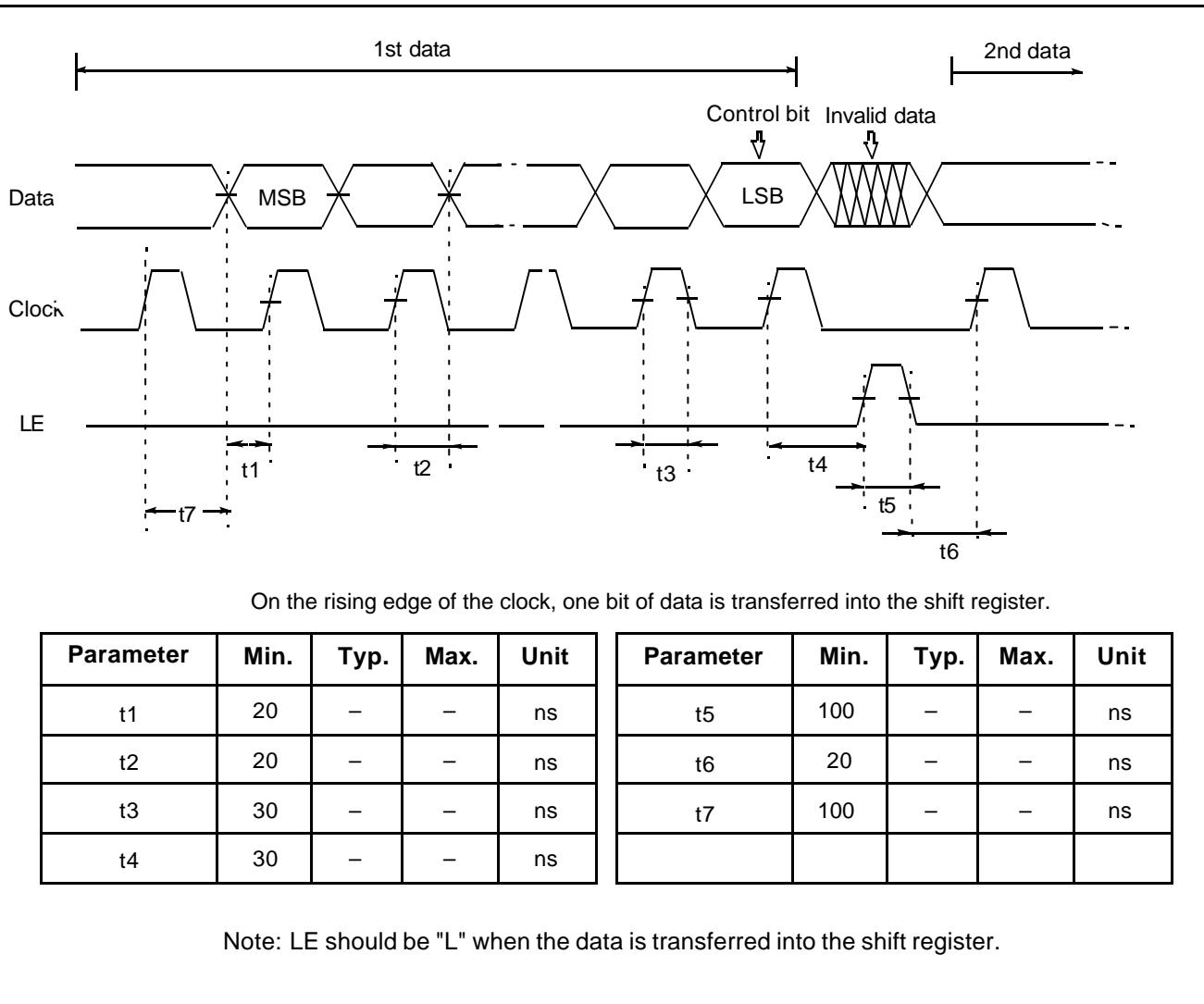
To prevent a major VCO frequency jump, the intermittent mode control circuit limits the magnitude of the error signal from the phase detector when it returns to normal operation.

Note: Note: When power (V_{CC}) is first applied, the device must be in standby mode, PS=Low, for at least 1μs.

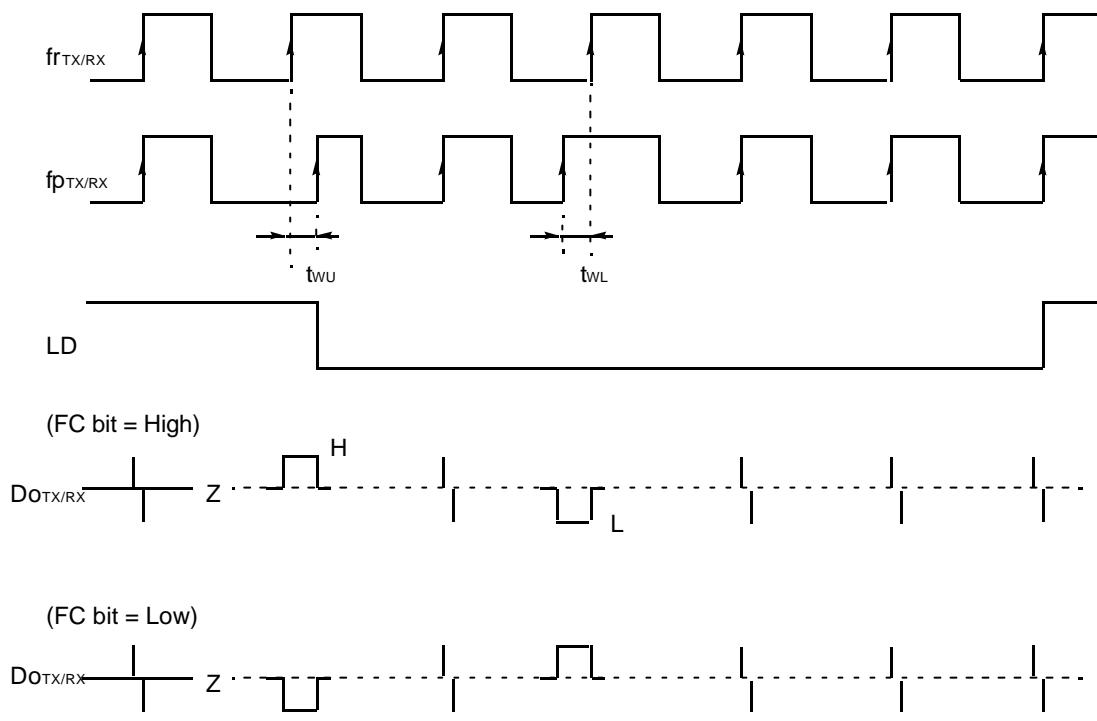
Note: PS pin must be set at "L" for Power ON.



■ SERIAL DATA INPUT TIMING



■ PHASE DETECTOR OUTPUT WAVEFORM

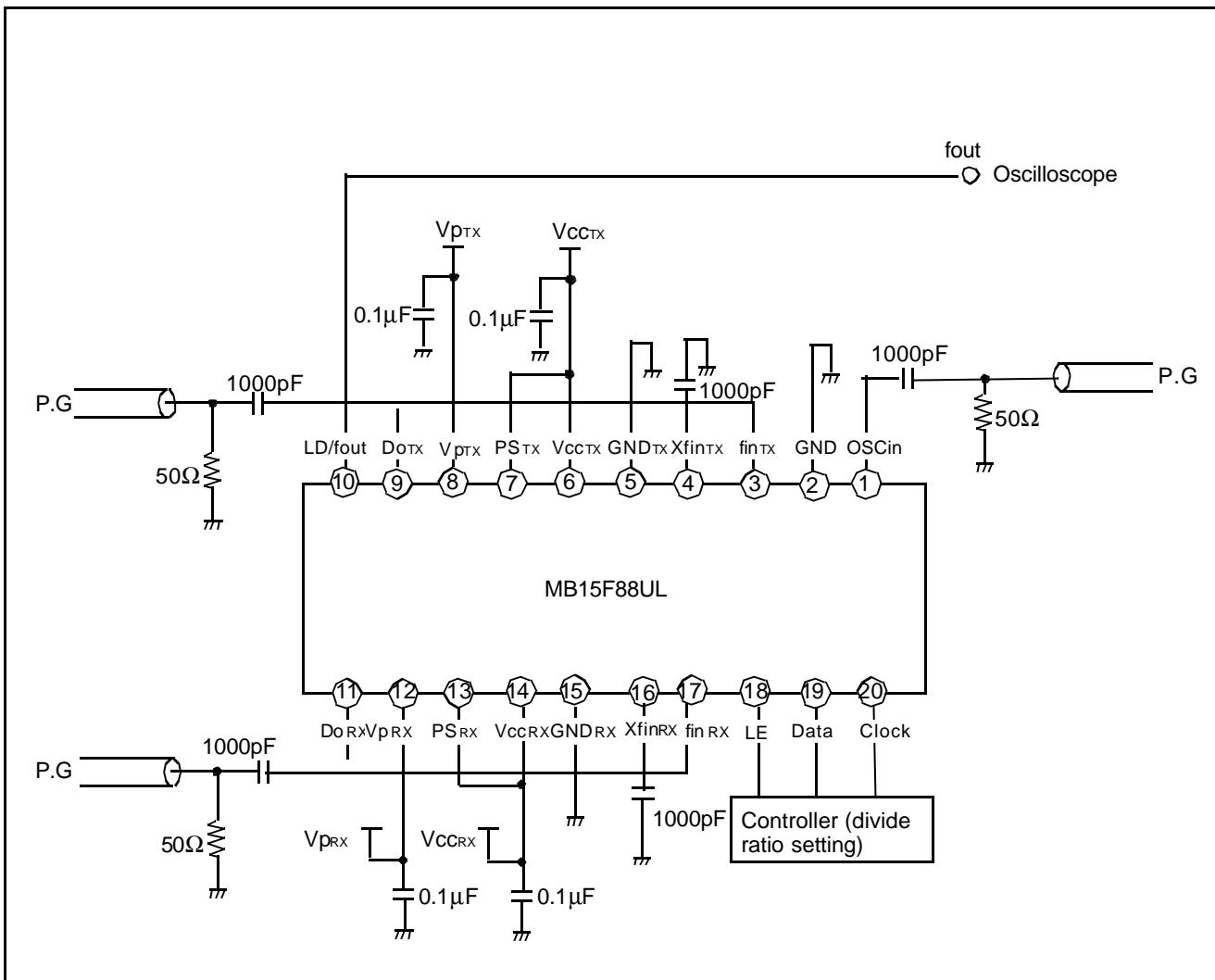


LD Output Logic Table

TX-PLL section	RX-PLL section	LD output
Locking state / Power saving state	Locking state / Power saving state	H
Locking state / Power saving state	Unlocking state	L
Unlocking state	Locking state / Power saving state	L
Unlocking state	Unlocking state	L

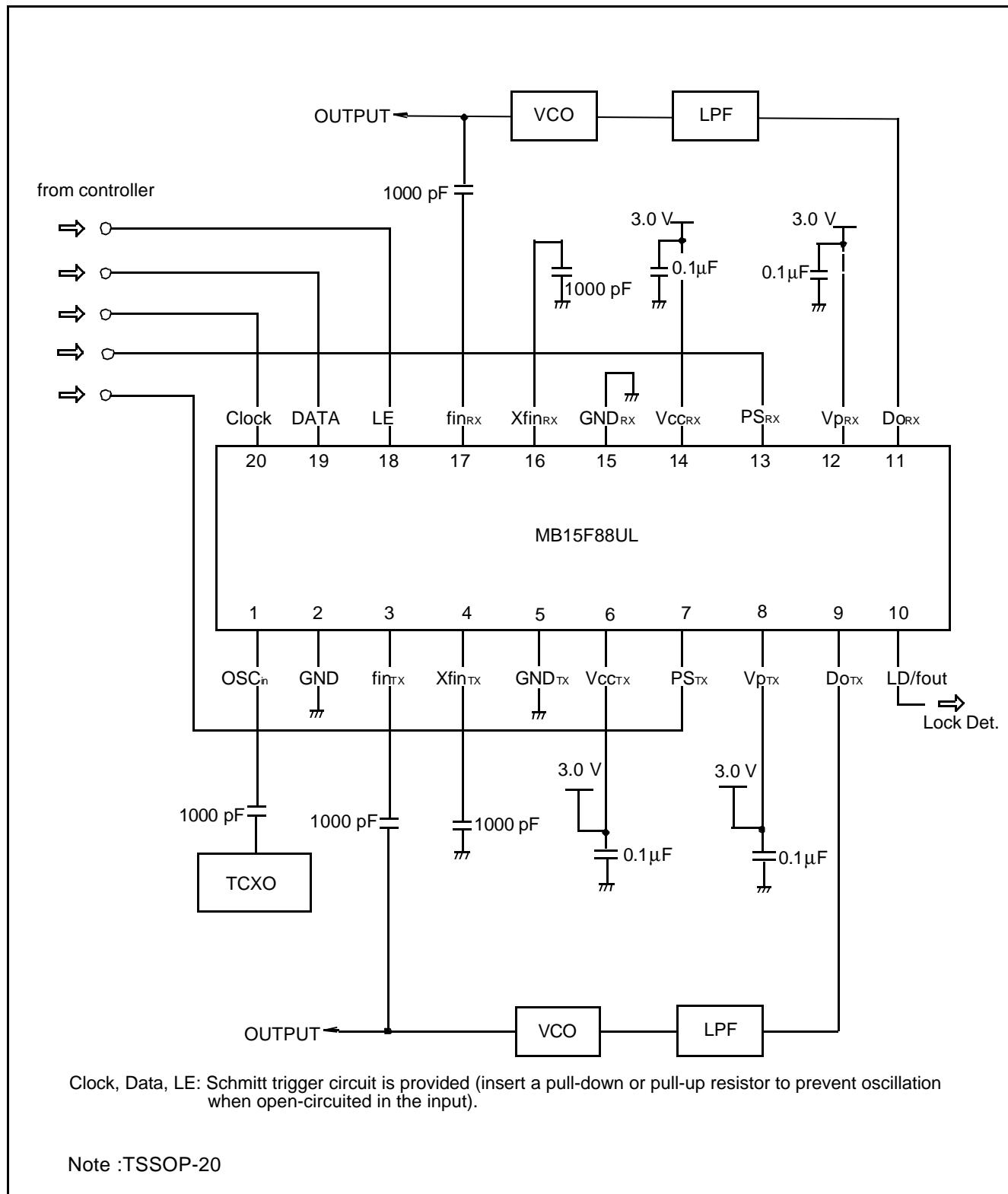
- Note:
- Phase error detection range = -2π to $+2\pi$
 - Pulses on $D_{OTX/RX}$ signals are output to prevent dead zone.
 - LD output becomes low when phase error is t_{WU} or more.
 - LD output becomes high when phase error is t_{WL} or less and continues to be so for three cycles or more.
 - t_{WU} and t_{WL} depend on OSCin input frequency as follows.
 $t_{WU} \geq 2/fosc$: i.e. $t_{WU} \geq 153.8\text{ns}$ when $fosc = 13\text{ MHz}$
 $t_{WL} \leq 4/fosc$: i.e. $t_{WL} \leq 307.6\text{ns}$ when $fosc = 13\text{MHz}$

■ TEST CIRCUIT (for Measuring Input Sensitivity fin/OSCin)



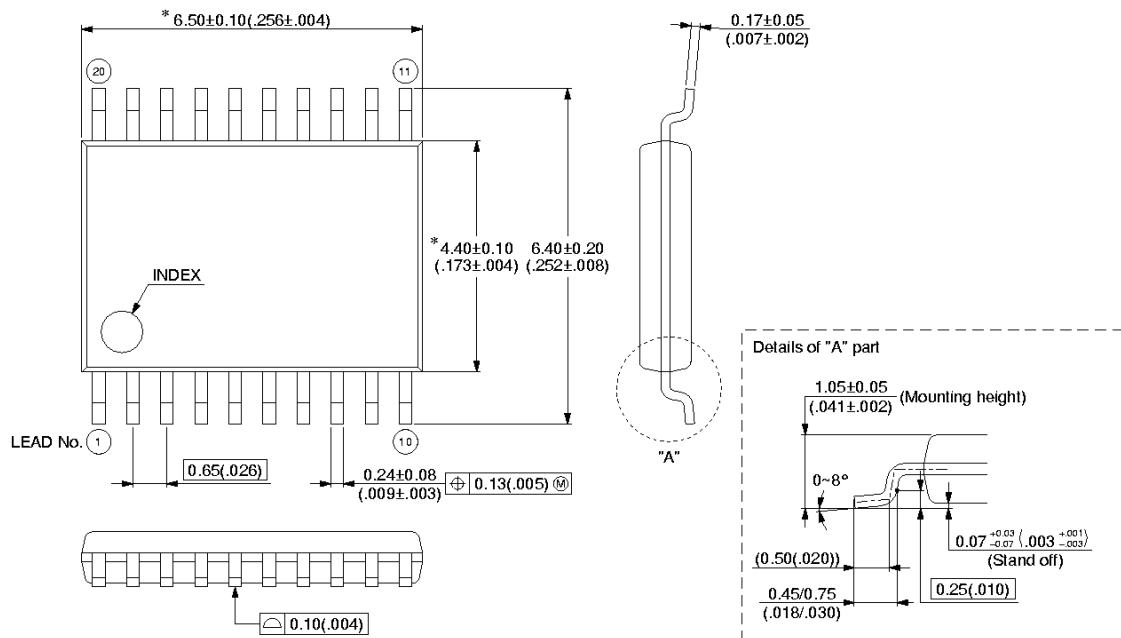
Note : TSSOP-20

■ APPLICATION EXAMPLE



■ PACKAGE DIMENSION20 pin, Plastic SSOP
(FPT-20P-M06)

*: These dimensions do not include resin protrusion.



© 1999 FUJITSU LIMITED F20026S-2C-2

(Continued)

(Continued)

20 pad, Plastic BCC
(LCC-20P-M05)

